



Material Content Data Sheet



Sales Product Name				XMC4200-Q48K256 BA		Issued		20. July 2018	
MA#				MA001360092					
Package				PG-VQFN-48-71		Weight*		135.54 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	10.110	7.46	7.46	74588	74588	
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		129		
	non noble metal	zinc	7440-66-6	0.070	0.05		518		
	non noble metal	iron	7439-89-6	1.403	1.04		10352		
wire	non noble metal	copper	7440-50-8	56.970	42.02	43.12	420323	431322	
	noble metal	palladium	7440-05-3	0.006	0.00		43		
	non noble metal	copper	7440-50-8	0.582	0.43	0.43	4291	4334	
encapsulation	organic material	carbon black	1333-86-4	0.184	0.14		1355		
	plastics	epoxy resin	-	9.614	7.09		70928		
	inorganic material	silicondioxide	60676-86-0	51.436	37.95	45.18	379489	451772	
leadfinish	noble metal	gold	7440-57-5	0.020	0.02		150		
	noble metal	palladium	7440-05-3	0.020	0.02		150		
	noble metal	silver	7440-22-4	0.020	0.02		150		
	non noble metal	nickel	7440-02-0	0.953	0.70	0.76	7031	7481	
plating	noble metal	palladium	7440-05-3	0.027	0.02		200		
	noble metal	silver	7440-22-4	0.027	0.02		200		
	noble metal	gold	7440-57-5	0.027	0.02		200		
	non noble metal	nickel	7440-02-0	1.276	0.94	1.00	9414	10014	
glue	plastics	epoxy resin	-	0.444	0.33		3278		
	noble metal	silver	7440-22-4	2.333	1.72	2.05	17211	20489	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com